

# IGBT Module U-Series 1200V / 100A 6 in one-package

## ■ Features

- High speed switching
- Voltage drive
- Low inductance module structure

## ■ Applications

- Inverter for Motor drive
- AC and DC Servo drive amplifier
- Uninterruptible power supply
- Industrial machines, such as Welding machines

## ■ Maximum ratings and characteristics

### ● Absolute maximum ratings (at $T_c=25^\circ\text{C}$ unless otherwise specified)

Item	Symbol	Conditions	Rating	Unit	
Collector-Emitter voltage	$V_{CES}$		1200	V	
Gate-Emitter voltage	$V_{GES}$		$\pm 20$	V	
Collector current	$I_c$	Continuous	$T_c=25^\circ\text{C}$	150	A
			$T_c=80^\circ\text{C}$	100	
	$I_{cp}$	1ms	$T_c=25^\circ\text{C}$	300	
			$T_c=80^\circ\text{C}$	200	
	$-I_c$			100	
$-I_c$ pulse			200		
Collector Power Dissipation	$P_C$	1 device	520	W	
Junction temperature	$T_j$		+150	$^\circ\text{C}$	
Storage temperature	$T_{stg}$		-40 to +125		
Isolation voltage	between terminal and copper base *1	$V_{iso}$	AC:1min.	2500	VAC
	between thermistor and others *2				
Screw Torque	Mounting *3		3.5	N·m	

\*1 : All terminals should be connected together when isolation test will be done.

\*2 : Two thermistor terminals should be connected together, each other terminals should be connected together and shorted to base plate when isolation test will be done.

\*3 : Recommendable value : 2.5 to 3.5 N·m(M5)

### ● Electrical characteristics (at $T_j=25^\circ\text{C}$ unless otherwise specified)

Item	Symbols	Conditions	Characteristics			Unit	
			Min.	Typ.	Max.		
Zero gate voltage collector current	$I_{CES}$	$V_{GE}=0V, V_{CE}=1200V$	–	–	1.0	mA	
Gate-Emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=\pm 20V$	–	–	200	nA	
Gate-Emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=20V, I_c=100mA$	4.5	6.5	8.5	V	
Collector-Emitter saturation voltage	$V_{CE(sat)}$ (terminal)	$V_{GE}=15V, I_c=100A$	$T_j=25^\circ\text{C}$	–	2.10	2.45	V
			$T_j=125^\circ\text{C}$	–	2.35	–	
	$V_{CE(sat)}$ (chip)		$T_j=25^\circ\text{C}$	–	1.75	2.10	
			$T_j=125^\circ\text{C}$	–	2.00	–	
Input capacitance	$C_{ies}$	$V_{CE}=10V, V_{GE}=0V, f=1MHz$	–	11	–	nF	
Turn-on time	$t_{on}$	$V_{CC}=600V$	–	0.36	1.20	$\mu s$	
	$t_r$	$I_c=100A$	–	0.21	0.60		
	$t_{r(i)}$	$V_{GE}=\pm 15V$	–	0.03	–		
Turn-off time	$t_{off}$	$R_G=5.6 \Omega$	–	0.37	1.00	$\mu s$	
	$t_f$		–	0.07	0.30		
Forward on voltage	$V_F$ (terminal)	$V_{GE}=0V, I_F=100A$	$T_j=25^\circ\text{C}$	–	1.95	2.25	V
			$T_j=125^\circ\text{C}$	–	2.05	–	
	$V_F$ (chip)		$T_j=25^\circ\text{C}$	–	1.60	1.90	
			$T_j=125^\circ\text{C}$	–	1.70	–	
Reverse recovery time	$t_{rr}$	$I_F=100A$	–	–	0.35	$\mu s$	
Lead resistance, terminal-chip*4	R lead		–	3.4	–	m $\Omega$	
Resistance	R	$T=25^\circ\text{C}$	–	5000	–	$\Omega$	
		$T=100^\circ\text{C}$	465	495	520		
B value	B	$T=25/50^\circ\text{C}$	3305	3375	3450	K	

\*4:Biggest internal terminal resistance among arm.

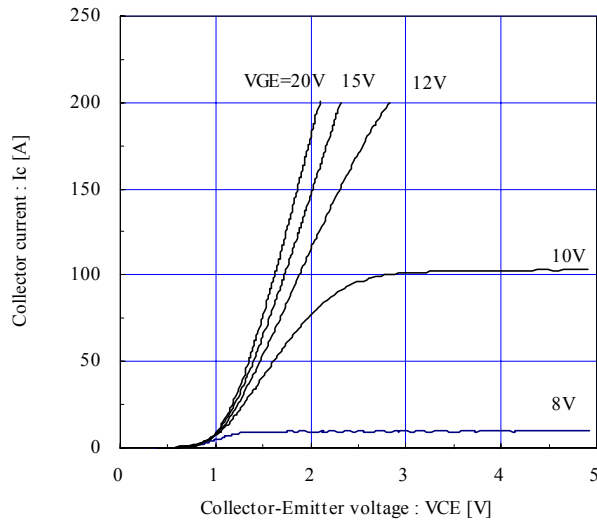
### ● Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Thermal resistance	$R_{th(j-c)}$	IGBT	–	–	0.24	$^\circ\text{C/W}$
	$R_{th(j-c)}$	FWD	–	–	0.39	$^\circ\text{C/W}$
Contact Thermal resistance	$R_{th(c-f)}$ *5	With thermal compound	–	0.05	–	$^\circ\text{C/W}$

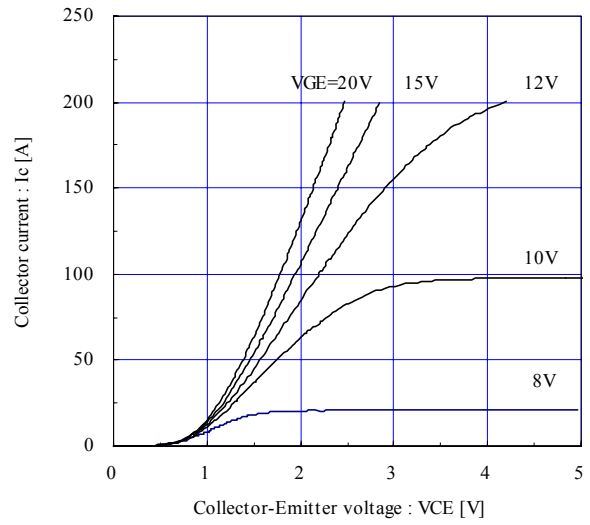
\*5 : This is the value which is defined mounting on the additional cooling fin with thermal compound.

Characteristics (Representative)

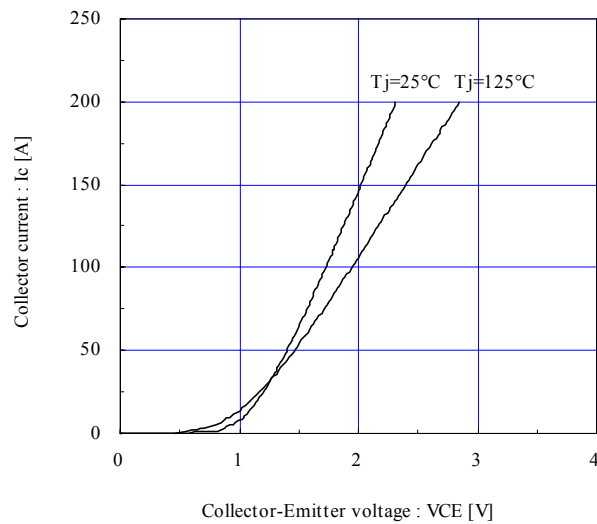
Collector current vs. Collector-Emitter voltage (typ.)  
Tj= 25°C / chip



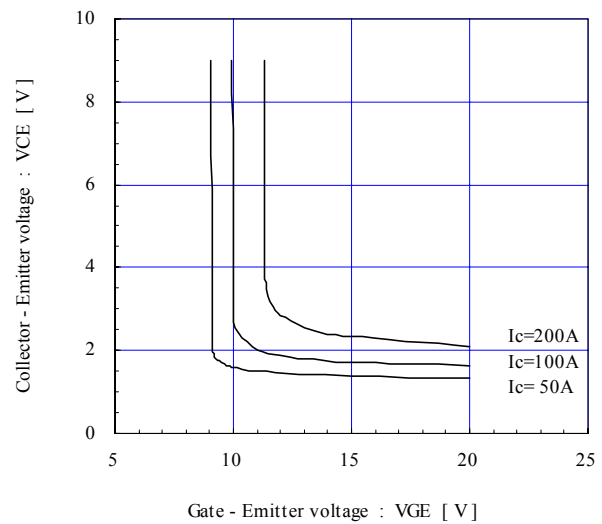
Collector current vs. Collector-Emitter voltage (typ.)  
Tj= 125°C / chip



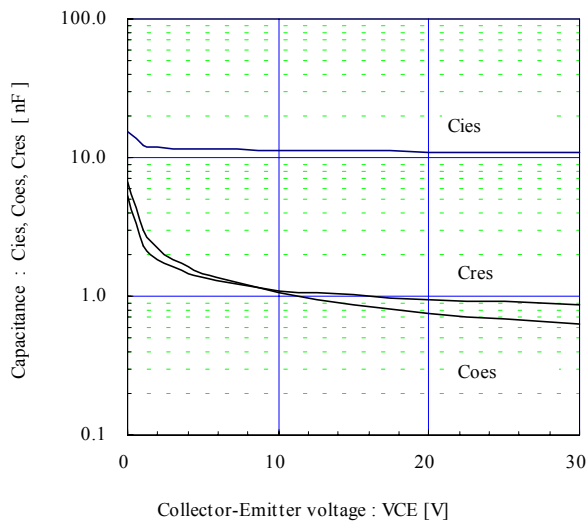
Collector current vs. Collector-Emitter voltage (typ.)  
VGE=15V / chip



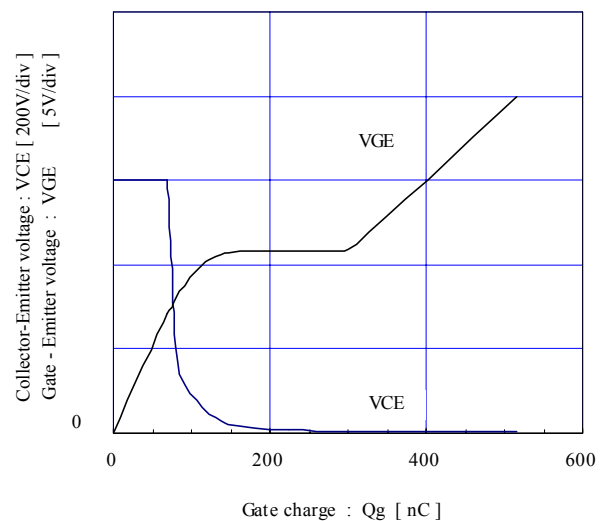
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)  
Tj=25°C / chip



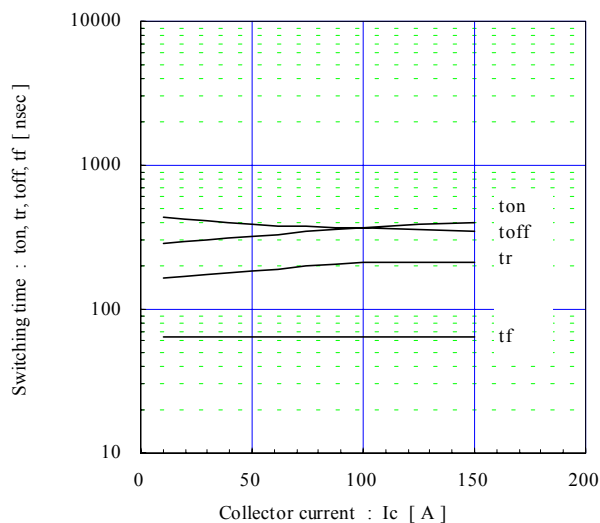
Capacitance vs. Collector-Emitter voltage (typ.)  
VGE=0V, f= 1MHz, Tj= 25°C



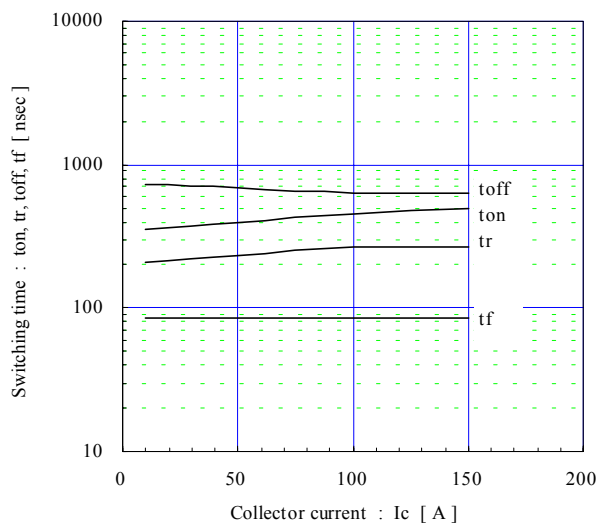
Dynamic Gate charge (typ.)  
Vcc=600V, Ic=100A, Tj= 25°C



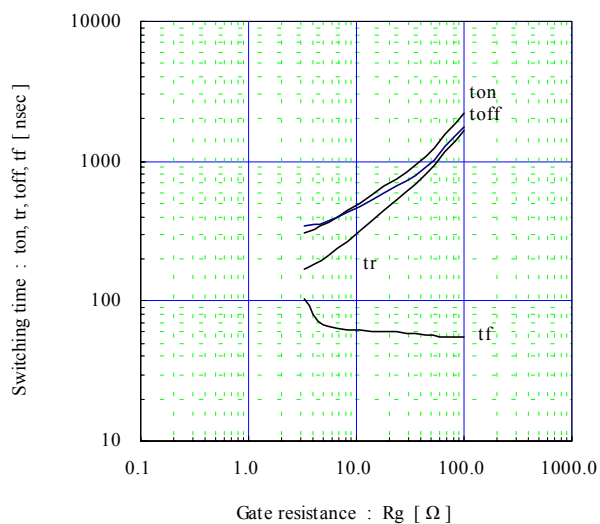
Switching time vs. Collector current (typ.)  
 $V_{cc}=600V, V_{GE}=\pm 15V, R_g=5.6\ \Omega, T_j=25^\circ C$



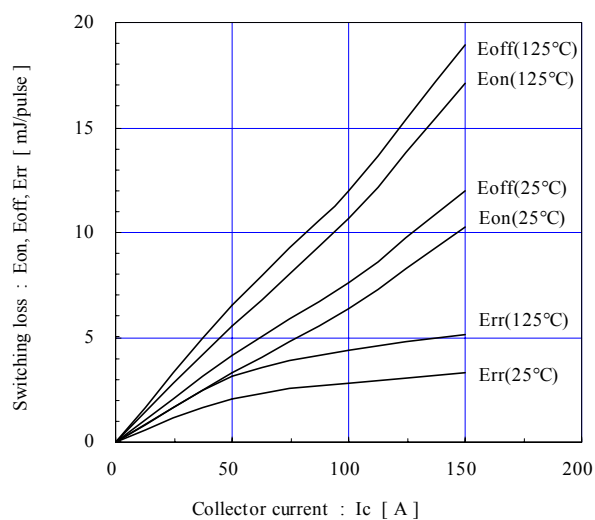
Switching time vs. Collector current (typ.)  
 $V_{cc}=600V, V_{GE}=\pm 15V, R_g=5.6\ \Omega, T_j=125^\circ C$



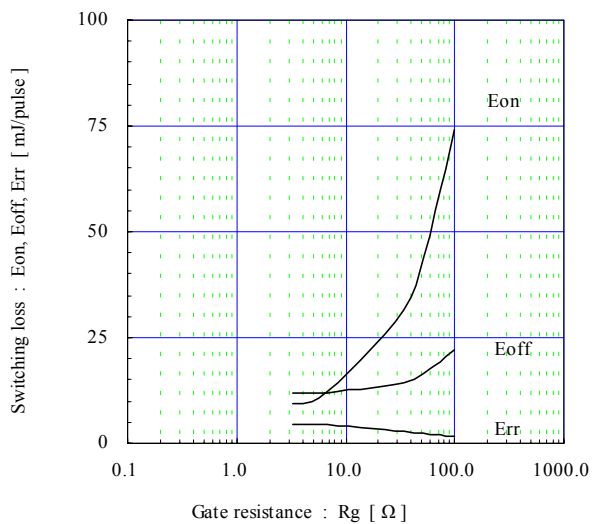
Switching time vs. Gate resistance (typ.)  
 $V_{cc}=600V, I_c=100A, V_{GE}=\pm 15V, T_j=25^\circ C$



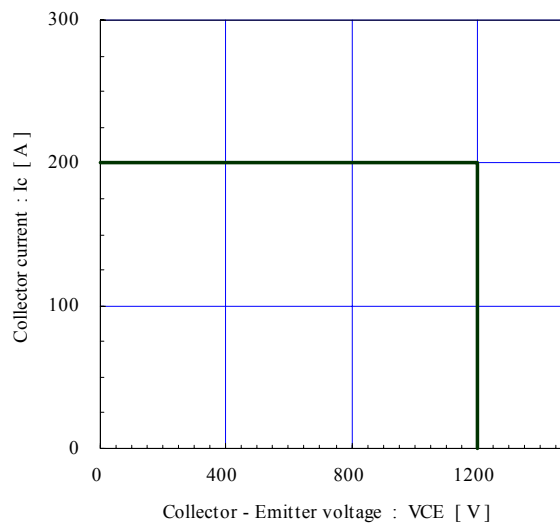
Switching loss vs. Collector current (typ.)  
 $V_{cc}=600V, V_{GE}=\pm 15V, R_g=5.6\ \Omega$



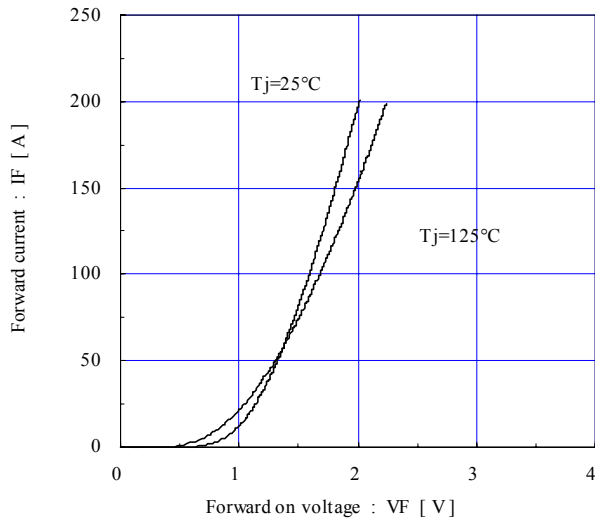
Switching loss vs. Gate resistance (typ.)  
 $V_{cc}=600V, I_c=100A, V_{GE}=\pm 15V, T_j=125^\circ C$



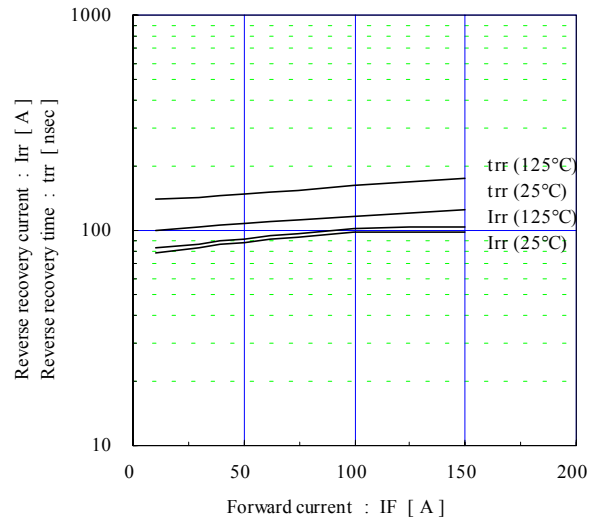
Reverse bias safe operating area (max.)  
 $+V_{GE}=15V, -V_{GE} \leq 15V, R_g \geq 5.6\ \Omega, T_j \leq 125^\circ C$



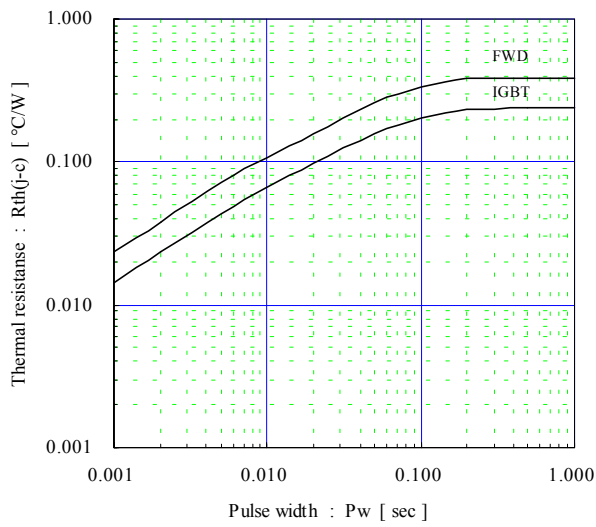
Forward current vs. Forward on voltage (typ.)  
chip



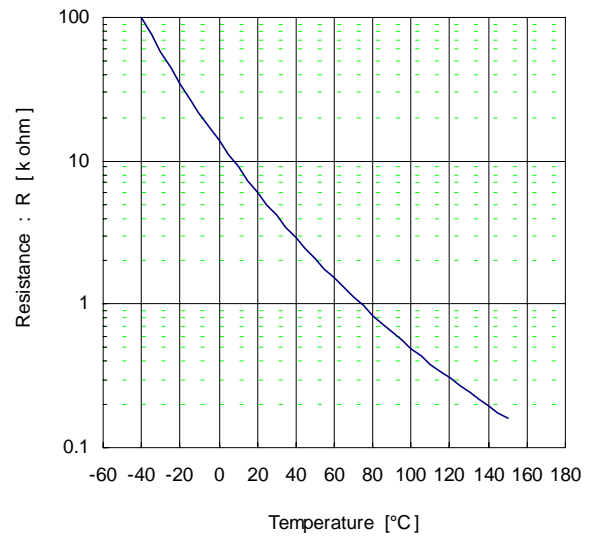
Reverse recovery characteristics (typ.)  
 $V_{cc}=600\text{V}, V_{GE}=\pm 15\text{V}, R_g=5.6\ \text{ohm}$



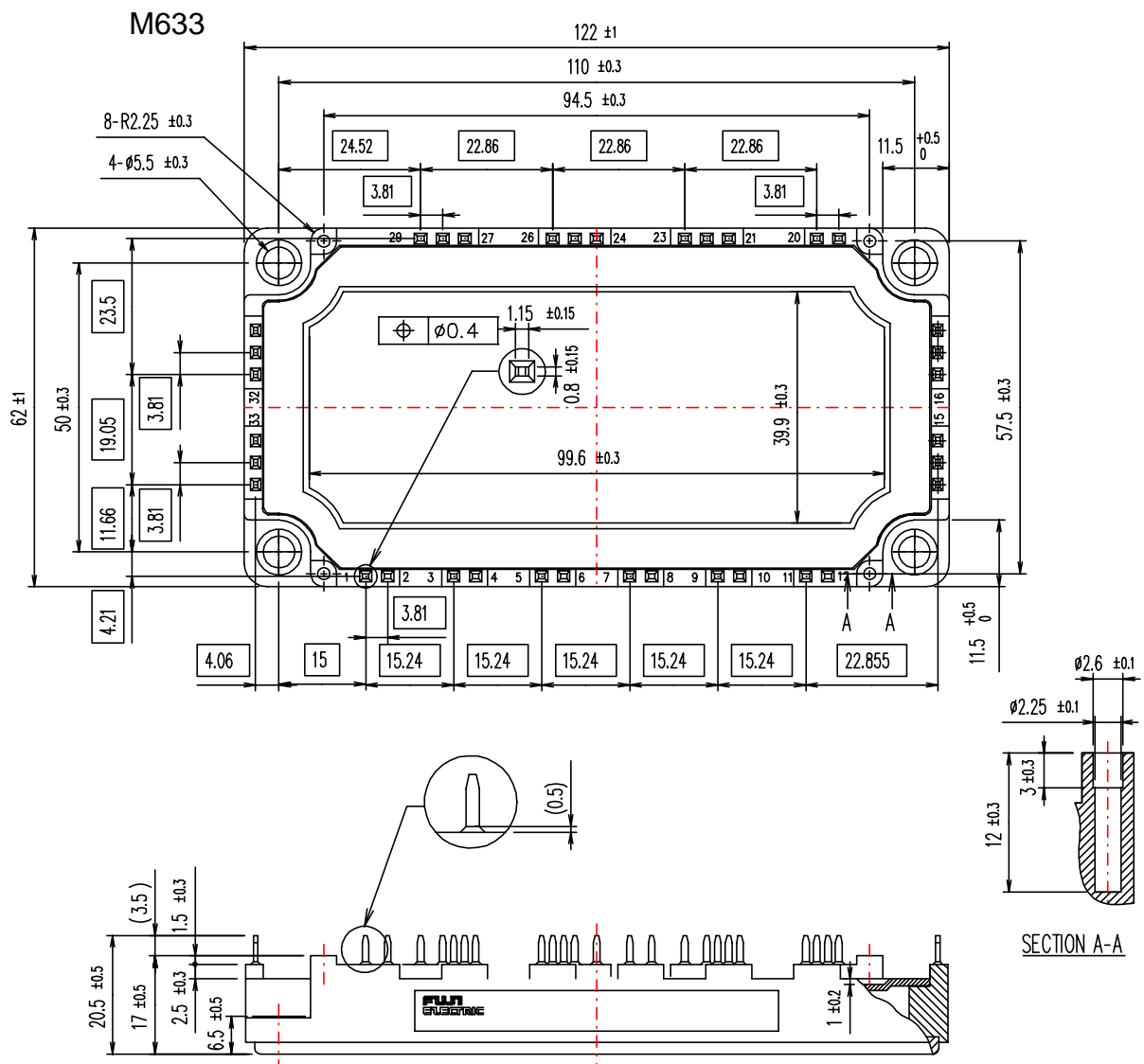
Transient thermal resistance (max.)



Temperature characteristic (typ.)



■ Outline Drawings, mm



□ shows theoretical dimension.  
 ( ) shows reference dimension.

■ Equivalent Circuit Schematic

